PCB Specification Document

Project Details

Specification name	GS-PCB-SPEC-0403
Release	1.0
Applicable projects	nanopower-p110c-qb50-1
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Specifications

	Specification	Remarks
Base Specification	IPC-A-6012 cl. 3/A	
Construction	Multi-layer	
Material	Glass/polyimide (GI) IPC-4101/40 Arlon 85N	
Surface finish	Hot oil SnPb reflow	
Layer count	4	
Dimensions	98.0 mm x 98.0 mm	
Packaging	Individually in ESD bag. 10 pcs. in bigger bag	MIL-P-116G IA-8

Panelization

	Specification	Remarks
Delivery in panel	☐	
Panel dimensions		
Array count X x Y		

File List

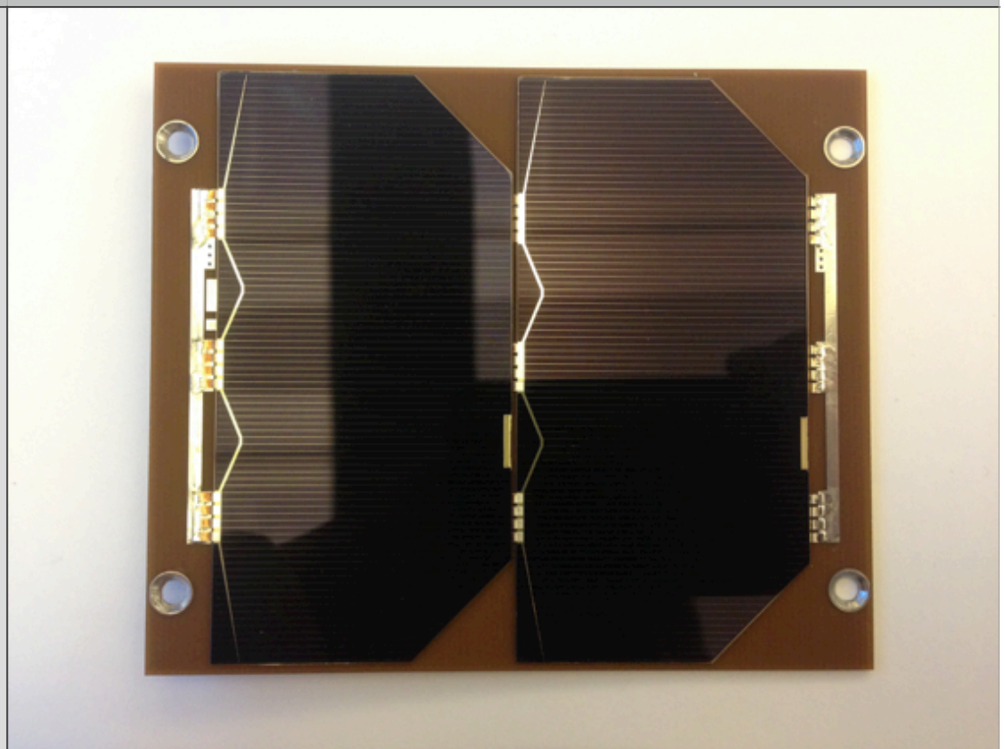
Layer	File	File Extension
Stencil top	N/A	GTP
Notation top	N/A	GM5
Copper top	project-name	GTL
Inner 1	project-name	G1
Inner 2	project-name	G2
Copper bottom	project-name	GBL
Notation bottom		GM8
Stencil bottom	N/A	GBP
Board outline	project-name	GM10
Drill through	project-name	TXT
Drill blind top	N/A	TX1
Drill blind bottom	N/A	TX2
Panel drawing	N/A	PDF

Special processes

	Check	Remarks
Notation top	☐	White low-outgassing epoxy
Notation bottom	☑	White low-outgassing epoxy, center of board, the following information in text (see photo on the next page): project-name year/week unique-identifier
Countersunk holes	☑	**3.2mm holes:** 90 degrees. 5.5mm top. **1.6mm holes:** 90 degrees. 3.75mm top.
Copper filled vias (type VII)	☑	All 0.3 mm drills
Hard gold contacts	☐	Filename
Electrical test	☑	
Impedance control	☐	Nets
Plasma etch-back	☑	
Plasma de-smearing	☑	
Manufacturer logo allowed	☐	

Build-up

	Thickness
Copper outer layers (incl. plating)	35 um
Copper inner layers	70 um
Thickness (over bare substrate)	1.1 mm

Top view Shows the top of a final, populated board. The four visible mounting holes are countersunk and plated.	
Bottom view Shows the bottom of a final, populated board. The notation in the center contains: project-name year/week unique-identifier